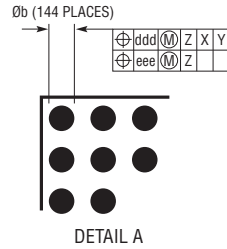
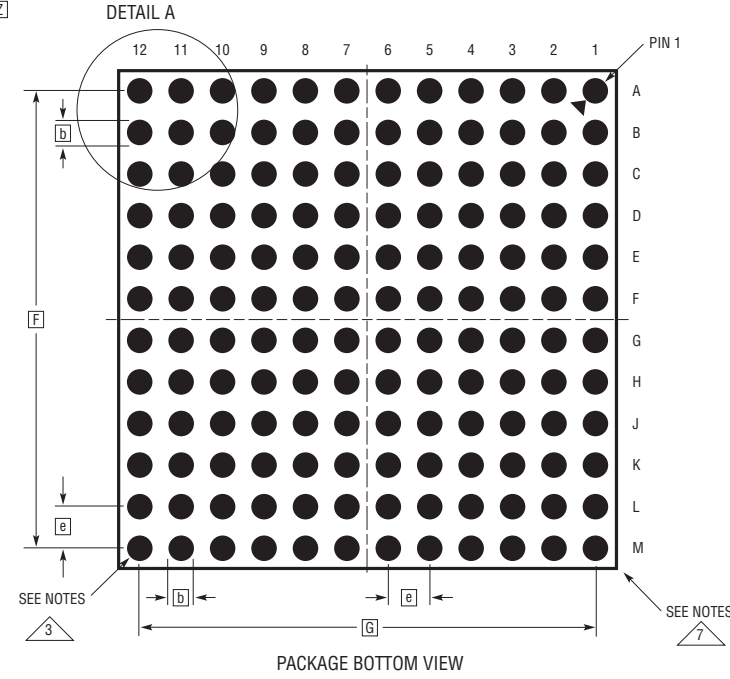
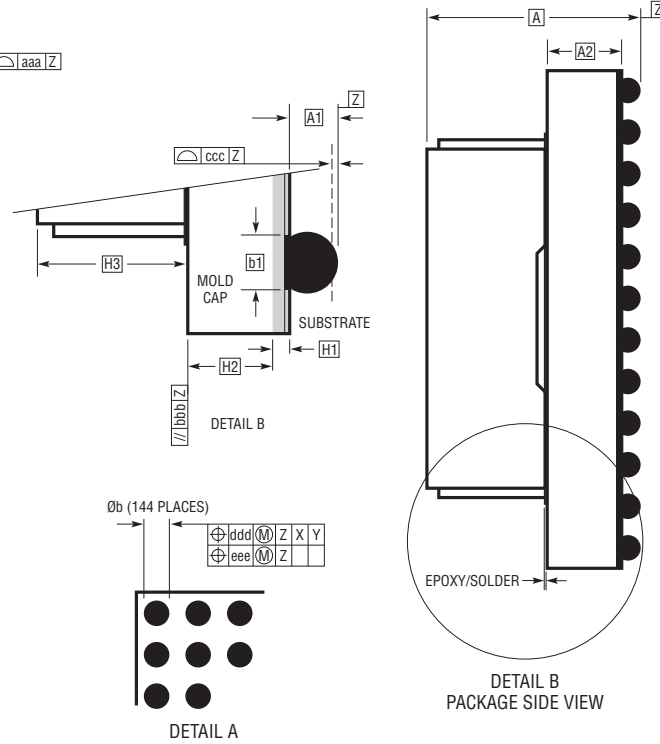
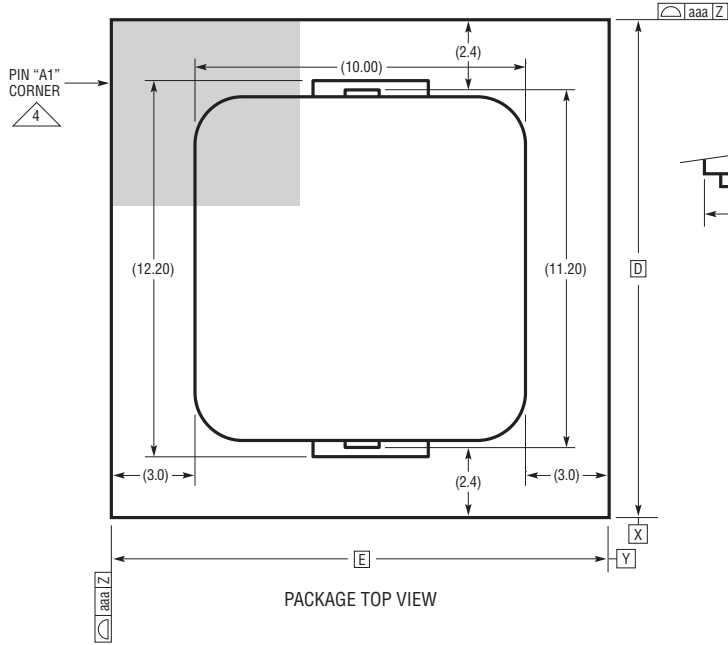
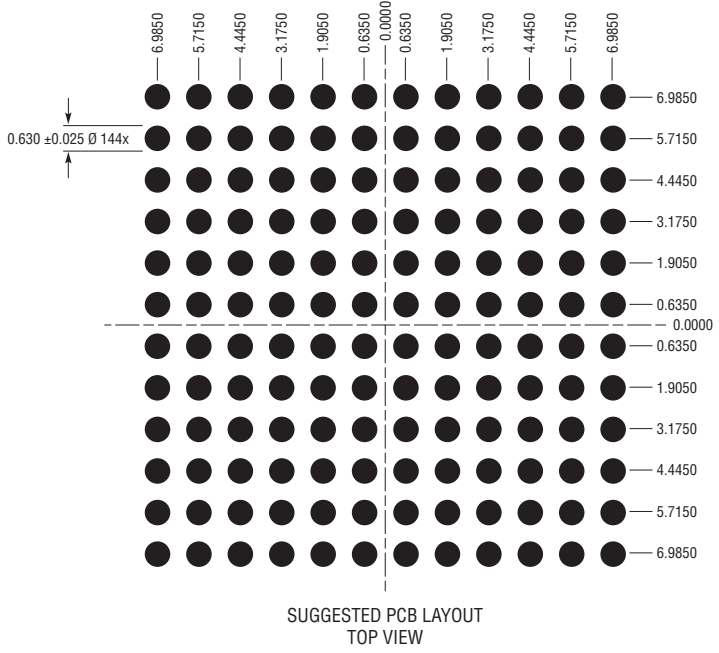


**BGA Package**  
**144-Lead (16mm × 16mm × 7.07mm)**  
 (Reference LTC DWG # 05-08-1562 Rev A)



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
  2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE
  - 3 BALL DESIGNATION PER JEP95
  - 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
  5. PRIMARY DATUM -Z- IS SEATING PLANE
  6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC
  - 7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



| DIMENSIONS |      |       |      |                |
|------------|------|-------|------|----------------|
| SYMBOL     | MIN  | NOM   | MAX  | NOTES          |
| A          | 6.57 | 7.07  | 7.42 |                |
| A1         | 0.50 | 0.60  | 0.70 | BALL HT        |
| A2         | 2.31 | 2.41  | 2.51 |                |
| b          | 0.60 | 0.75  | 0.90 | BALL DIMENSION |
| b1         | 0.60 | 0.63  | 0.66 | PAD DIMENSION  |
| D          |      | 16.00 |      |                |
| E          |      | 16.00 |      |                |
| e          |      | 1.27  |      |                |
| F          |      | 13.97 |      |                |
| G          |      | 13.97 |      |                |
| H1         | 0.36 | 0.41  | 0.46 | SUBSTRATE THK  |
| H2         | 1.95 | 2.00  | 2.05 | MOLD CAP HT    |
| H3         | 3.76 | 4.06  | 4.21 | INDUCTOR HT    |
| aaa        |      |       | 0.15 |                |
| bbb        |      |       | 0.10 |                |
| ccc        |      |       | 0.20 |                |
| ddd        |      |       | 0.30 |                |
| eee        |      |       | 0.15 |                |

TOTAL NUMBER OF BALLS: 144

